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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ray *et al.*

Examiner: Nguyen, Ha T

Serial No.: 09/779,812 ✓

Art Unit: 2812

Filed: 2/08/01

For: LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE

Commissioner for Patents
Washington D.C. 20231

Sir:

This paper is being filed in response to a Office Action dated November 20, 2002 in connection with the above-identified application. Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

At the time of filing the present patent application, Applicants submitted an Information Disclosure Statement which listed the reference of Australian Patent AU-B-68124/90 (Ogashiwa, published 07/91). Applicants also submitted a copy of this reference with the originally filed present patent application, but have recently discovered that several pages were missing from said originally submitted copy of this reference. Applicants have therefore arranged to obtain a complete copy, with no pages missing, of this reference. Accordingly, Applicants will submit to the U.S.P.T.O., for the record, said complete copy of this reference as soon as Applicants obtain said complete copy of this reference. Applicants respectfully request that the Examiner consider this reference in its entirety after the U.S.P.T.O. receives said complete copy of this reference.